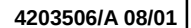


## METAL SINGLE-IN-LINE MODULE



- NOTES:
- |                                                              |                                                                                                                                 |
|--------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------|
| A. All linear dimensions are in inches (mm).                 | G. Solder mask openings to copper island for solder joints to mechanical pins. Electrically connect case to power ground plane. |
| B. This drawing is subject to change without notice.         | H. Power pin connections should utilize two or more vias per input, ground and output pin.                                      |
| C. 2 place decimals are $\pm 0.030$ ( $\pm 0,76\text{mm}$ ). | I. Case outline reference                                                                                                       |
| D. 3 place decimals are $\pm 0.010$ ( $\pm 0,25\text{mm}$ ). |                                                                                                                                 |
| E. Recommended mechanical keep out area.                     |                                                                                                                                 |
| F. Vias are recommended to improve copper adhesion.          |                                                                                                                                 |

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